



**DOW CORNING**

## Press Information

**Dow Corning Corporation**  
A wholly owned subsidiary of  
The Dow Chemical Company  
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## **Dow Corning<sup>®</sup> TC-5888 Thermally Conductive Compound Improves Production, Performance and Reliability of High-End Electronics**

**MIDLAND, Mich. – Oct 19, 2017** – Dow Corning, a wholly owned subsidiary of The Dow Chemical Company and a global leader in silicones, silicon-based technology and innovation, today introduced new *Dow Corning<sup>®</sup> TC-5888 Thermally Conductive Compound*. The latest addition to the Company's broad and growing portfolio of solutions for thermal management, the new material is tailored to address the design and manufacturing challenges associated with high-performance server applications.

"With the continued growth in cloud computing, data networks and telecom infrastructure, the demand for reliable server designs continues to grow as quickly as the demands on their performance," said Grace Zhang, strategic marketing manager, Dow Corning. "TC-5888 Thermally Conductive Compound addresses both of these challenges by combining excellent thermal management for improved server reliability with a flow profile that enhances both productivity and precision."

TC-5888 Thermally Conductive Compound offers the highest bulk thermal conductivity in Dow Corning's thermally conductive compound product portfolio. The material's combination of high thermal conductivity (5.2 W/m.K) along with its ability to achieve thin Bond Line Thickness (BLT) of approximately 20 microns yields low thermal resistance of 0.05 (C.cm<sup>2</sup>/W). The end result is a thermal compound that efficiently dissipates heat to improve performance and reliability of high sensitive server processors.

New TC-5888 thermal compound also features unique rheological properties that limit its flow beyond a target interface once assembled. This flow characteristic distinguishes it from lower viscosity thermal compounds, and provides greater control for applications requiring a thicker thermal compound layer or greater precision when dispensing compound between surface interfaces – such as in between large server packages and corresponding heat sinks. TC-5888 Thermally Conductive Compound also offers low volatile content vs. competitive thermal compounds, allowing for more consistent rheology, application repeatability and easier screen printing overall.

*Dow Corning<sup>®</sup> TC-5888 Thermally Conductive Compound* is commercially available worldwide. The company's broad portfolio of advanced thermally conductive adhesives, encapsulants, gels and compounds are especially designed to enable improved performance for many of today's most demanding applications.

### **About DowDuPont Materials Science Division**

DowDuPont Materials Science, a business division of DowDuPont (NYSE: DWDP), combines science and technology knowledge to develop premier materials science solutions that are essential to human progress. The division has one of the strongest and broadest toolkits in the industry, with robust technology, asset integration, scale and competitive capabilities that enable it to address complex global issues. DowDuPont Materials Science's market-driven, industry-leading portfolio of advanced materials, industrial intermediates, and plastics businesses deliver a broad range of differentiated technology-based products and solutions for customers in high-growth markets such as packaging, infrastructure, and consumer care. DowDuPont intends to separate the Materials Science Division into an independent, publicly traded company. More information can be found at [www.dow-dupont.com](http://www.dow-dupont.com).

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New *Dow Corning*<sup>®</sup> TC-5888 Thermally Conductive Compound Designed to Improve Production, Performance and Reliability of High-End Servers

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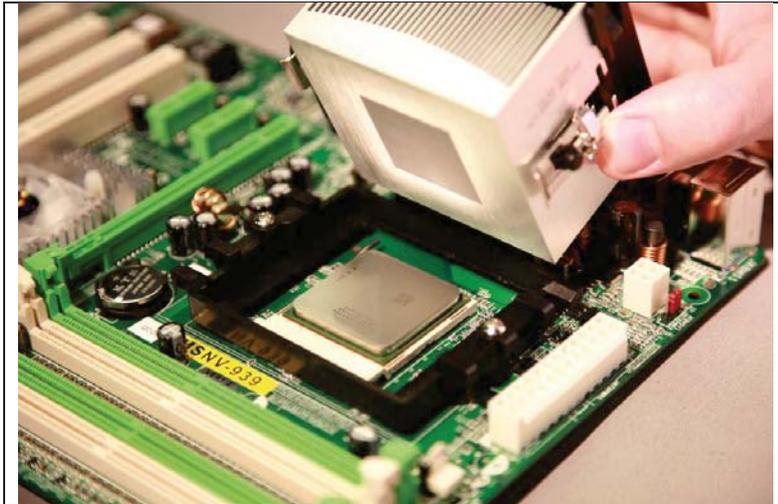
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